

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7928381

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ZVI OR-BACH	02/04/2023
BRIAN CRONQUIST	02/04/2023
DEEPAK SEKAR	02/05/2023
RECEIVING PARTY DATA	
Name:	MONOLITHIC 3D INC.
Street Address:	1662 COVE POINT RD
City:	KLAMATH FALLS
State/Country:	OREGON
Postal Code:	97601
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18105881
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4088399533
Email:	Brian@MonolithIC3D.com
Correspondent Name:	BRIAN CRONQUIST
Address Line 1:	1662 COVE POINT RD
Address Line 4:	KLAMATH FALLS, OREGON 97601
ATTORNEY DOCKET NUMBER:	M3D-C-ISCON5
NAME OF SUBMITTER:	BRIAN CRONQUIST
SIGNATURE:	/Brian Cronquist/
DATE SIGNED:	04/30/2023
Total Attachments: 3	
source=M3D_C-IScon5_Assignment_Zvi---signed#page1.tif	
source=M3D_C-IScon5_Assignment_Brian---signed#page1.tif	
source=M3D_C-IScon5_Assignment_Deepak---signed#page1.tif	

ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

**A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH
IMAGE SENSORS AND WAFER BONDING**

as described in US Application Serial No. 18/tbd and filed on or about February 04, 2023; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 02 / 04 / 2023

(**Zvi**

First Name

PO-110 '23

Middle Initial

Or-Bach)

Last Name

PATENT

REEL: 063488 FRAME: 0183 -e26668f6

ASSIGNMENT

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in Klamath Falls, Oregon;** have made a certain invention, and executed United States Patent Application entitled:

**A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH
IMAGE SENSORS AND WAFER BONDING**

as described in US Application Serial No. 18/tbd filed on or about February 04, 2023; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called “Assignee”), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the “Designated Countries”).

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

Brian Cronquist

DATE on 02 / 04 / 2023

(Brian

Cronquist)

First Name

Middle Initial

Last Name

PATENT

☐ **REEL: 063488 FRAME: 0184** la5d8463d5

ASSIGNMENT

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in Sunnyvale, California;** have made a certain invention, and executed United States Patent Application entitled:

**A MULTILEVEL SEMICONDUCTOR DEVICE AND STRUCTURE WITH
IMAGE SENSORS AND WAFER BONDING**

as described in U.S. Application Serial No. 18/tbd filed on or about February 04, 2023; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 02 / 05 / 2023

(Deepak

First Name

Deepak C. Sekar

Middle Initial

Sekar)

Last Name

PATENT

RECORDED: 04/30/2023

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